Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

HP x360 310 G2 PC
HP x360 310 G2
HP x360 310

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm PCA</td>
<td>3</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Battery pack:RCT</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries N/A</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LED</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink,</td>
<td>Include the cartridges, print heads, tubes, vent</td>
<td>0</td>
</tr>
</tbody>
</table>
including liquids, semi-liquids (gel/paste) and toner chambers, and service stations. N/A

| Components and waste containing asbestos | N/A | 0 |
| Components, parts and materials containing refractory ceramic fibers | N/A | 0 |
| Components, parts and materials containing radioactive substances | N/A | 0 |

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Phillips screwdriver (for 9 PCS on bottom case)</td>
<td>#1 2.5~3.0 kg-cm</td>
</tr>
<tr>
<td>Description #2 Phillips screwdriver (for 7 PCS on motherboard)</td>
<td>#1 2.5~3.0 kg-cm</td>
</tr>
<tr>
<td>Description #3 Phillips screwdriver (for 2 PCS on left side IO board)</td>
<td>#1 2.5~3.0 kg-cm</td>
</tr>
<tr>
<td>Description #4 Phillips screwdriver (for 7 PCS on base side hinge bracket)</td>
<td>#1 2.5~3.0 kg-cm</td>
</tr>
<tr>
<td>Description #5 Use jig disassembly Lcd Bezel with Lcd cover</td>
<td>Pick thickness 0.3~0.4mm</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Release 9 PCS Phillips screw for Bottom case figure 1.
2. Disassemble Topcase Pls refere figure 2.
3. Disassemble Battery caonn. pls refere figure 3.
4. Disassemble KB FFC、TP FFC、speaker conn。、IO FFC、Power FFC、EDP FFC、Touch FFC、HDD FFC figure 4.
6. Teardown mainboard & Right side IO board.
8. Disassemble LCD Bezel by jig pls refer figure 7.
9. Disassemble touch control board cable pls refer figure 8
10. Disassemble LCD cable Pls refer figure 9.
11. Release 8Pcs Phillips screw on hinge Bracket Pls refer figure 10
12. 

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Use #1 screwdriver to disassemble 9 Pcs screw.

Two hand together to disassemble Upper case from arrow side.

Figure 1

#1 Phillips screwdriver

Figure 2

First disassembly: battery conn.

First disassembly: KB FFC, TP FFC, speaker conn., IO FFC, Power FFC, EDP FFC, Touch FFC, HDD FFC.

Figure 3

Figure 4

PSG instructions for this template are available at EL-MF877-01
Use #1 screwdriver Disassembly 7 Pcs screw
Teardown mainboard

Figure 5

#1 Phillips screwdriver

Use #1 screwdriver Disassembly 7 Pcs screw
Teardown LCD module

Figure 6

#1 Phillips screwdriver

Disassemble LCD module initial step Use pick insert gap between LCD Bezel and LCD cover

Figure 7

Disassemble touch control FFC

Figure 8

Pick thickness range from 0.3mm to 0.4mm

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Disassemble EDP cable

Figure 9

Use #1 screwdriver Disassemble 8 Pcs screw
Teardown hinge bracket

Figure 10

PSG instructions for this template are available at EL-MF877-01